



## Product End-of-Life Disassembly Instructions

**Product Category: Notebooks and Tablet PCs**

**Marketing Name / Model:**  
**[List multiple models if applicable.]**

**HP Spectre x360 13 Convertible PC**

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact [HP's Sustainability Contact](#).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Main board/Touch board/IR board/Audio board/Power board/FPR module/Touch Pad module	7
Batteries, excluding Li-Ion batteries.	All types including standard alkaline, coin or button style batteries	0
Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)	Battery(ies) are attached to the product by ( <i>check all that apply with an "x" inside the "[ ]"</i> ): [x] screws [ ] snaps [ ] adhesive [ ] other. Explain _____ NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	DC Cable for External Power Supply	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs)		

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Item Description	Notes	Quantity of items included in product
already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	#0,#1

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove base rubber foot \*2, base screw \*4 and base sub-assy.
2. Release battery connector and batter screw \*5 and remove battery
3. Release front L/R speaker connector, remove front L/R speaker screw \*6 and remove front L/R speaker.
4. Remove SSD shield can screw \*1 ,remove SSD shield can and take out SSD.
5. Remove Black Mylar , release M/B side FPR connector/ TP connector /KB connector / BL connector/PWR connector /AD connector/SPK connector \*2/LVDS connector/Fan connector \*2 /camera connector/Wlan connector/IR connector
6. Remove Fan screw \*4 and take out fan \*2
7. Remove M/B screw \*4 and take out M/B
8. Remove audio board screw \*1 and take out audio board
9. Remove FPR screw \*2 and take out FPR. bracket /FPR
10. Remove TP screw \*3 and take out TP
11. Remove Power board screw and take out power board
12. Remove Hinge screw \*4 and LCD module assy
13. Remove rear L/R speaker screw \*2 and take out rear L/R speaker.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part

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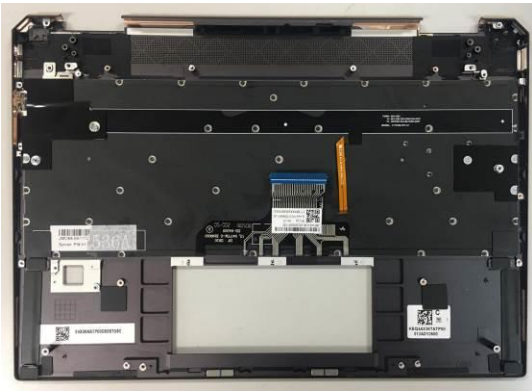
3.22 Remove front / rear side rubber , base screw and base sub assy.



3.23 Remove black Mylar, battery, SSD, SSD shield can, Rear L/R fan, Power board



3.24 Remove Front L/R speaker ,TP module ,Rear L/R speaker, FPR , FPR bracket ,FPR FFC , Audio board ,M/B



### 3.25 The LCD module is not disassembly

